FLIP CHIP ASSEMBLY PROCESS FOR ULTRA THIN SUBSTRATE AND PACKAGE ON PACKAGE ASSEMBLY

ABSTRACT

In some embodiments, selective electroless plating for electronic substrates is presented. In this regard, a method is introduced including receiving a coreless substrate strip, attaching solder balls to a backside of the coreless substrate strip, and forming a backside stiffening mold amongst the solder balls. Other embodiments are also disclosed and claimed.

FIG. 1